





**Thermal and Mechanical Spec** 

Thermal performance for 80W CPU HSK Assembly Weight: 294 g

## Application

Passive solution for Intel® Nehalem processor in 2U rack-mounted server LGA 1366





## **Component Specifications**

Application System	20+ Form Factor Passive Solution
Material	Aluminum extrusion
Dimension	89 x 89 x 63 mm
Fastener	Screw + Spring
Thermal interface	Shin Etsu X23-7762
Material	SIIII LISU A25-7702

\*All readings are typical values at rated voltage.

\*Specifications are subjected to change without notice.